

STANDARDS NEWSLETTER

(INDIA REGION)

Volume 4

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Deliver on Consistency, Reliability and Quality

MESSAGE

It's heartening to observe the progress of Standard Development activities in India Region. First time India region member companies participated in global IPC events for IPC A-610 and IPC/WHMA A-620 Groups. I'm sure, with their participation, other India member companies will also be encouraged to participate in forthcoming global events and have their involvement in the resolution of comments received for next revisions.

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David Bergman
VP - Standards & Technology

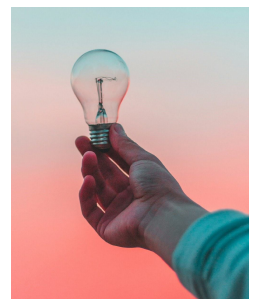
CALL FOR PARTICIPATION!

7-14a In-System Programming Task Group

This task group will develop IPC-9271 Guidelines for In-System Programming and will provide a set of standardized guidelines and best industry practices on In-circuit or in-system testing and programming at device level. The main topics in scope of this document are PCB design for ISP, integration of the programmer in the production environment and fundamental characteristics when choosing an ISP programmer.

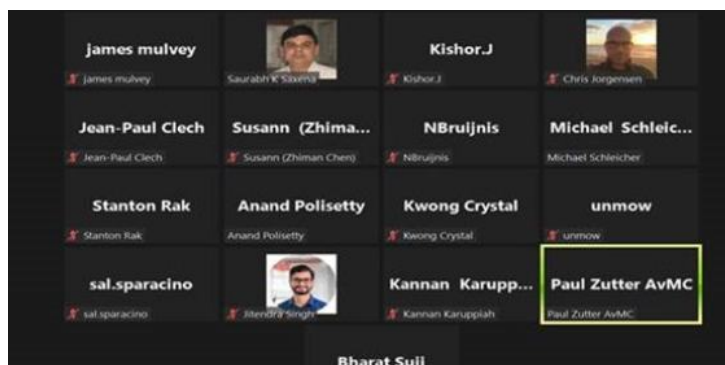
Rail Transit Addendum to IPC/WHMA-A-620

IPC/WHMA-A-620FR,
Rail Transit Addendum to IPC/
WHMA-A-620F (Requirements and
Acceptance for Cable and Wire
Harness Assemblies)



INITIATIVES

Recently, two new projects 6-10K (IPC 9911, Guideline for Automotive Electronics Printed Board Thermal Management & Electronic Component Derating) and 6-10J (IPC 2232, Guideline for Printed Board Design and Manufacturing of IoT Products) have been started with its project Launch Meetings.



These projects are having global footprints from India, USA, UK, Germany, China, South Korea, Hongkong, Italy, Netherlands, Denmark and Italy and are expected to be completed by 2027.

Consumer Electronics – Enhancing Manufacturing Process Quality Standards

IPC has teamed up with India Cellular and Electronics Association (ICEA) to study, find & improvise “Standards” applicable for design & manufacturing process in the assembly of printed circuit boards used in building consumer electronics devices, gadgets & appliances.

Against this drive, IPC India has developed a task group consisting Industry Members, Government organisation, Subject Matter Experts and brainstorming on the challenges and issues faced by consumer electronics sector and subsequently working on recommendations & develop content/curriculum for training/skill development.

PCB Test Lab @ India

IPC India along with PCB industry is working for getting an Indian Mil Standard equivalent to the USA Mil 55110 / 31032 and putting in place the procedure (Audit and Certification of manufacturers) and Testing of PCBs to Mil Spec so that there is a whole Eco System in place for Indian PCB manufacturers to supply PCBs that are specified to be meeting USA MIL 55110 / 31032.



IPC has plans to showcase the progress and having an awareness session of this initiative along with all stake holders and rest of related audience in its flagship event – IEMI event in July 2024.

IPC STANDARDS DEVELOPMENT COMMITTEE MEETINGS

(India region) review session was held at Bengaluru on January 30, 2024 for Electronics Manufacturing Services (EMS) & Wire Harness comprising members from India, Malaysia, UAE, South Africa and Sri Lanka.

In these meetings, total 30 participants Joined physically and virtually to discuss on IPC-610, IPC - JSTD001 and IPC-620 Standards, IPC 9911 and IPC 2232. During these session, team leaders presented the progress to VP-Standards and Technology (Mr. David Bergman) and Executive Director (Mr. Gaurab Majumdar).



STANDARD REVIEW MEETINGS

IPC India will be hosting Standard Review Meetings in its flagship event – IEMI (Integrated Electronics Manufacturing & Interconnections) event on 29th July 2024. During these session, Chairs and Project team members will be showcasing the progress and next actions ahead to VP-Standards and Technology (Mr. David Bergman).



INDIA REGION MEMBERS PARTICIPATION IN GLOBAL IPC EVENTS

Wintercom, Barcelona

At IPC Wintercom 2024 event (22-25 January'2024) for standards committee meetings at Barcelona Spain, IPC India regional committee members actively participated in IPC- 610 and IPC-620 Task Group Meetings. During these session, members actively participated in the resolution of comments received from global.



IPC 1771 – AUTOMOTIVE SUPPLIER CHECKLIST

On February 17, a technical awareness session has been conducted at Pune, India for IPC 1771, Checklist for Automotive Suppliers'. This check sheet is to minimize the variance in auditing practices of OEM's at supplier sites, thereby enabling suppliers to focus resources on process improvement and product reliability. It is also going to help PCBA Suppliers understand and be better prepared for automotive requirements which again truly matches with IPC objective of Build Electronics Better.

This session has been attended by Automotive OEM, Suppliers and highly appreciated the IPC efforts for coming out with this checklist.



STANDARDS: CURRENT STATUS

Published Standards

IPC-A-610J	Acceptability of Electronic Assemblies
J-STD-001J	Requirements for Soldered Electrical and Electronic Assemblies
IPC-6012FS	Space and Military Avionics Application Addendum to IPC-6012F, Qualification and Performance Specification for Rigid Printed Boards
IPC-4922	Requirements for Sintering Materials for Electronics Assembly
IPC-7711/21D	Rework, Modification and Repair of Electronic Assemblies

Project Approved

IPC-2221C	Generic Standard on Printed Board Design
IPC-1602A	Standard for Printed Board Handling and Storage
IPC-2201	Requirements for Physics of Failure Analysis for Components and Assemblies
IPC-2611A	Generic Requirements for Electronic Product Documentation
IPC-2612-1A	Sectional Requirements for Electronic Diagramming Symbol Generation Methodology
IPC-4204C	Flexible Metal-Clad Dielectrics for Use in Fabrication of Flexible Printed Boards
IPC-6911	Acceptability of Additively Manufactured Electronics (AME)
IPC-6931	Requirements and Acceptance of Optical Module Printed Boards
IPC-7070	Guidelines for Printed Board Component Mounting
IPC-HDBK-001A	Handbook and Guide to Supplement J-STD-001G and J-STD-001G - Revision A
IPC-HDBK-850A	Guidelines for Design, Selection and Application of Potting Materials and Encapsulation Processes Used for Electronics Printed Circuit Board Assembly
IPC/JEDEC J-STD-033E	Handling, Packing, Shipping and Use of Moisture, Reflow, and Process Sensitive Devices
IPC/JEDEC J-STD-609C	Marking, Symbols, and Labels of Leaded and Lead-Free Terminal Finished Materials Used in Electronic Assembly
J-STD-001JA/ IPC-A-610JA	Automotive Addendum to IPC J-STD-001J Requirements for Soldered Electrical and Electronic Assemblies and IPC-A-610J Acceptability of Electronic Assemblies



For more information, please contact:

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